

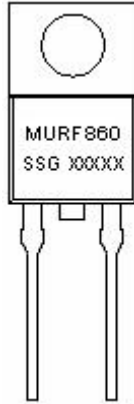


# THE DATASHEET OF MURF860





**Marking Diagram:**



Where XXXXX is YYWWL

MUR = Device Type  
 F = Package type  
 8 = Forward Current (8A)  
 60 = Reverse Voltage (600V)  
 SSG = SSG  
 YY = Year  
 WW = Week  
 L = Lot Number

**Cautions:** Molding resin  
 Epoxy resin UL:94V-0

**Ordering Information:**

Device	Package	Shipping
MURF860	ITO-220AC (Pb-Free)	50pcs / tube

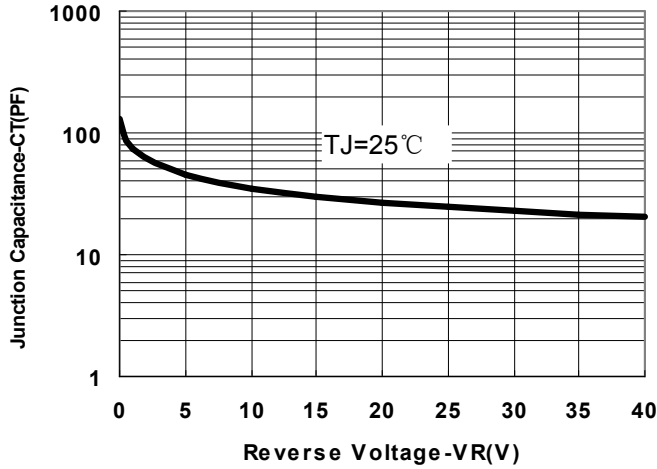
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

**Maximum Ratings and Electrical Characteristics** @ $T_A=25^\circ\text{C}$  unless otherwise specified

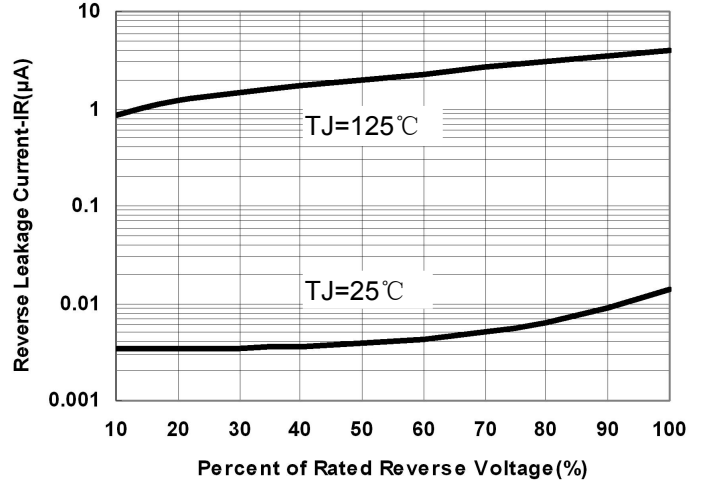
Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	MURF860	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	600	V
RMS Reverse Voltage	$V_{R(RMS)}$	420	V
Average Rectified Output Current @ $T_A = 55^\circ\text{C}$	$I_o$	8.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	110	A
Forward Voltage (per element) @ $I_F = 8.0\text{A}$ , $T_J=25^\circ\text{C}$	$V_{FM1}$	2.2	V
@ $I_F = 8.0\text{A}$ , $T_J=100^\circ\text{C}$	$V_{FM2}$	2.0	V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	$I_{RM}$	5 50	$\mu\text{A}$
Maximum Reverse Recovery Time (Note 1)	$T_{rr}$	50	ns
Max. Voltage Rate of Change	$dv/dt$	10,000	V/ $\mu\text{s}$
Typical Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	25	K/W
Storage Temperature Range	$T_{STG}, T_J$	-55 to +150	$^\circ\text{C}$
Approximate Weight	wt	1.6	g
Case Style	ITO-220AC		

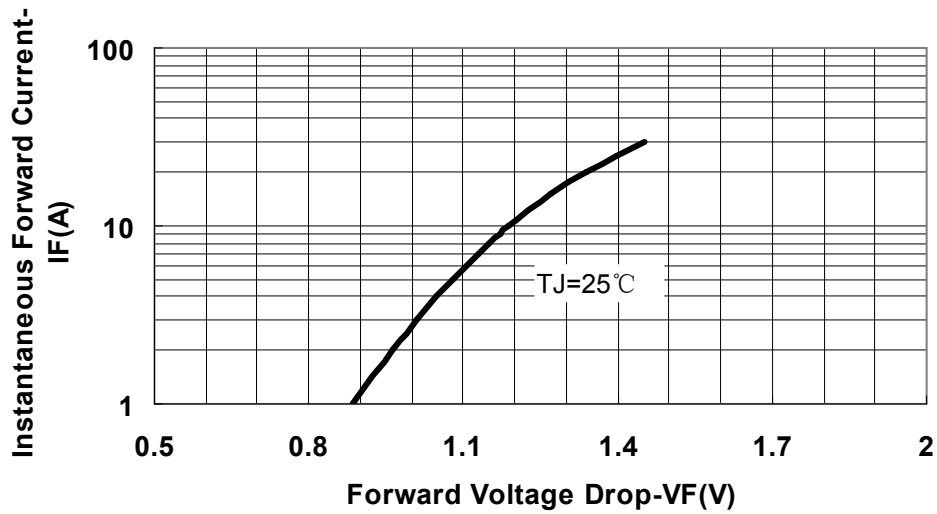
Note: 1. Reverse Recovery Test Conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$   
2. Mount on Cu-Pad Size 16mm×16mm on P.C.B.



**Fig.1-Typical Junction Capacitance**



**Fig.2-Typical Reverse Characteristics**





**Fig.3-Typical Forward Voltage Drop Characteristics**

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